

BAS21W series

High-voltage switching diodes

Rev. 01 — 9 October 2009

Product data sheet

1. Product profile

1.1 General description

High-voltage switching diodes, encapsulated in a very small Surface-Mounted Device (SMD) plastic package.

Table 1. Product overview

Type number	Configuration	Package		Package configuration
		NXP	JEDEC	
BAS21W	single	SOT323	SC-70	very small
BAS21AW	dual common anode			
BAS21SW	dual series			

1.2 Features

- High switching speed: $t_{rr} \leq 50$ ns
- Low leakage current
- High reverse voltage: $V_R \leq 250$ V
- Low capacitance: $C_d \leq 2$ pF
- Very small SMD plastic package
- AEC-Q101 qualified

1.3 Applications

- High-speed switching
- General-purpose switching
- Voltage clamping
- Reverse polarity protection

1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
I_F	forward current		[1] -	-	225	mA
I_R	reverse current	$V_R = 200$ V	-	-	100	nA
V_R	reverse voltage		-	-	250	V
t_{rr}	reverse recovery time		[2] -	-	50	ns

[1] Single diode loaded.

[2] When switched from $I_F = 10$ mA to $I_R = 10$ mA; $R_L = 100$ Ω ; measured at $I_R = 1$ mA.

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
BAS21W			
1	anode		 006aaa764
2	not connected		
3	cathode		
BAS21AW			
1	cathode (diode 1)		 006aab099
2	cathode (diode 2)		
3	common anode		
BAS21SW			
1	anode (diode 1)		 006aaa763
2	cathode (diode 2)		
3	cathode (diode 1), anode (diode 2)		

3. Ordering information

Table 4. Ordering information

Type number	Package		Version
	Name	Description	
BAS21W	SC-70	plastic surface-mounted package; 3 leads	SOT323
BAS21AW			
BAS21SW			

4. Marking

Table 5. Marking codes

Type number	Marking code ^[1]
BAS21W	X4*
BAS21AW	X6*
BAS21SW	X5*

- [1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
Per diode						
V_R	reverse voltage		-	250	V	
I_F	forward current		^[1] -	225	mA	
			^[2] -	125	mA	
I_{FRM}	repetitive peak forward current		-	625	mA	
I_{FSM}	non-repetitive peak forward current	square wave	^[3]			
		$t_p = 1 \mu s$		-	9	A
		$t_p = 100 \mu s$		-	3	A
		$t_p = 10 ms$		-	1.7	A
Per device						
P_{tot}	total power dissipation	$T_{amb} \leq 25 \text{ }^\circ\text{C}$	^[4] -	200	mW	
T_j	junction temperature		-	150	$^\circ\text{C}$	
T_{amb}	ambient temperature		-55	+150	$^\circ\text{C}$	
T_{stg}	storage temperature		-65	+150	$^\circ\text{C}$	

[1] Single diode loaded.

[2] Double diode loaded.

[3] $T_j = 25 \text{ }^\circ\text{C}$ prior to surge.

[4] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per device						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	625	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	300	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

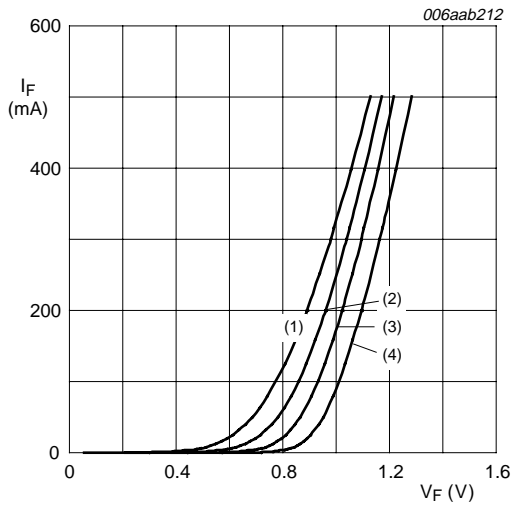
7. Characteristics

Table 8. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

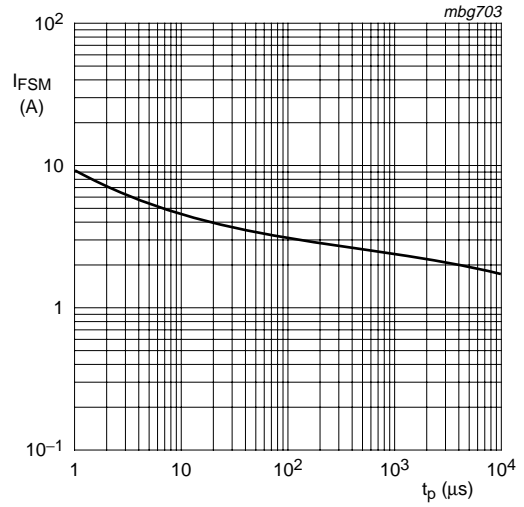
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
V_F	forward voltage	$I_F = 100\text{ mA}$	-	-	1.0	V
		$I_F = 200\text{ mA}$	-	-	1.25	V
I_R	reverse current	$V_R = 200\text{ V}$	-	-	100	nA
		$V_R = 200\text{ V}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	100	μA
C_d	diode capacitance	$f = 1\text{ MHz}; V_R = 0\text{ V}$	-	-	2	pF
t_{rr}	reverse recovery time		[1]	-	50	ns

[1] When switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}$; $R_L = 100\text{ }\Omega$; measured at $I_R = 1\text{ mA}$.



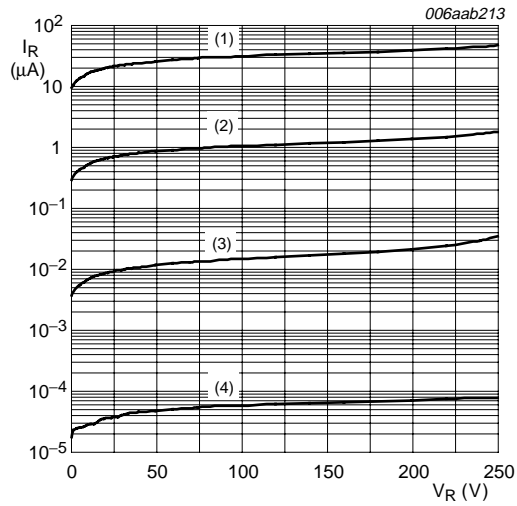
- (1) $T_{amb} = 150\text{ °C}$
- (2) $T_{amb} = 85\text{ °C}$
- (3) $T_{amb} = 25\text{ °C}$
- (4) $T_{amb} = -40\text{ °C}$

Fig 1. Forward current as a function of forward voltage; typical values



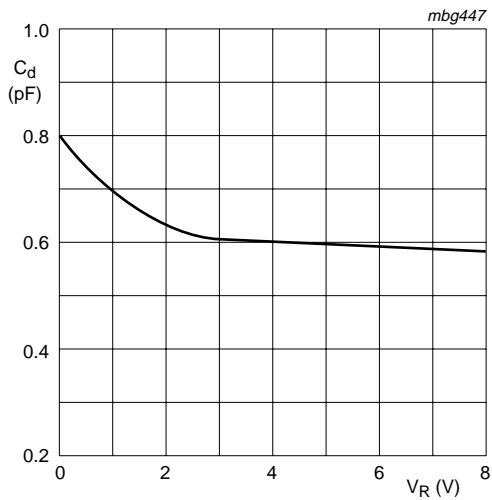
Based on square wave currents.
 $T_j = 25\text{ °C}$; prior to surge

Fig 2. Non-repetitive peak forward current as a function of pulse duration; maximum values



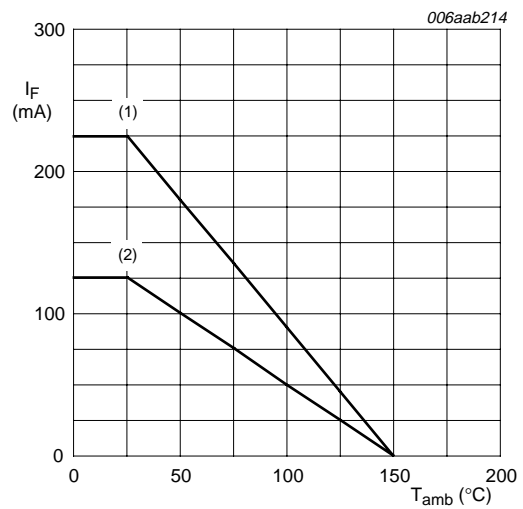
- (1) $T_{amb} = 150\text{ °C}$
- (2) $T_{amb} = 85\text{ °C}$
- (3) $T_{amb} = 25\text{ °C}$
- (4) $T_{amb} = -40\text{ °C}$

Fig 3. Reverse current as a function of reverse voltage; typical values



f = 1 MHz; T_{amb} = 25 °C

Fig 4. Diode capacitance as a function of reverse voltage; typical values

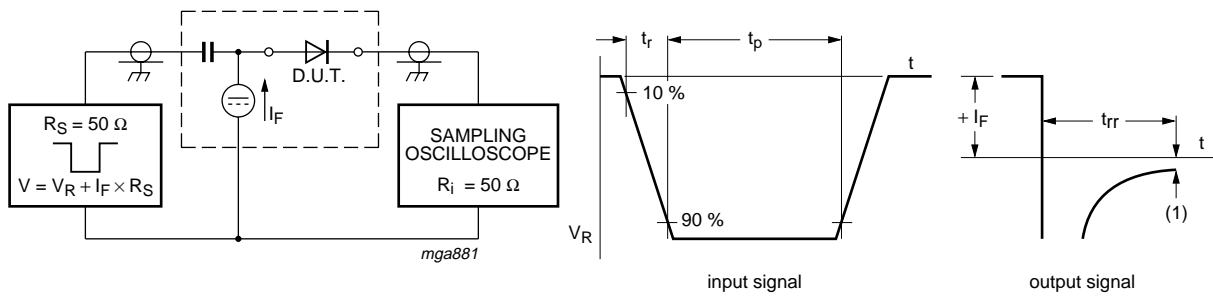


FR4 PCB, standard footprint

- (1) Single diode loaded.
- (2) Double diode loaded.

Fig 5. Forward current as a function of ambient temperature; derating curve

8. Test information



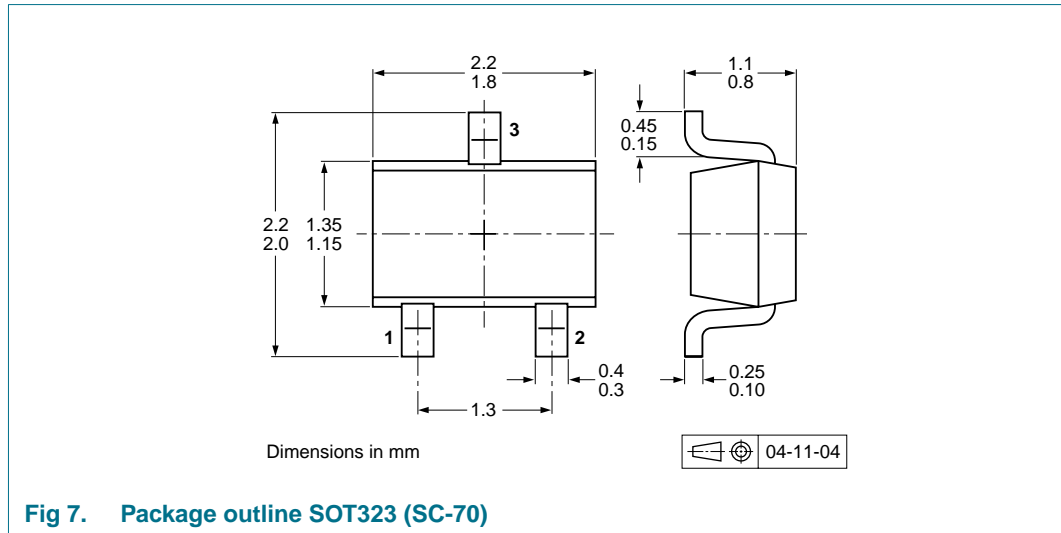
(1) I_R = 1 mA

Fig 6. Reverse recovery time test circuit and waveforms

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



10. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			3000	10000
BAS21W	SOT323	4 mm pitch, 8 mm tape and reel	-115	-135
BAS21AW				
BAS21SW				

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering

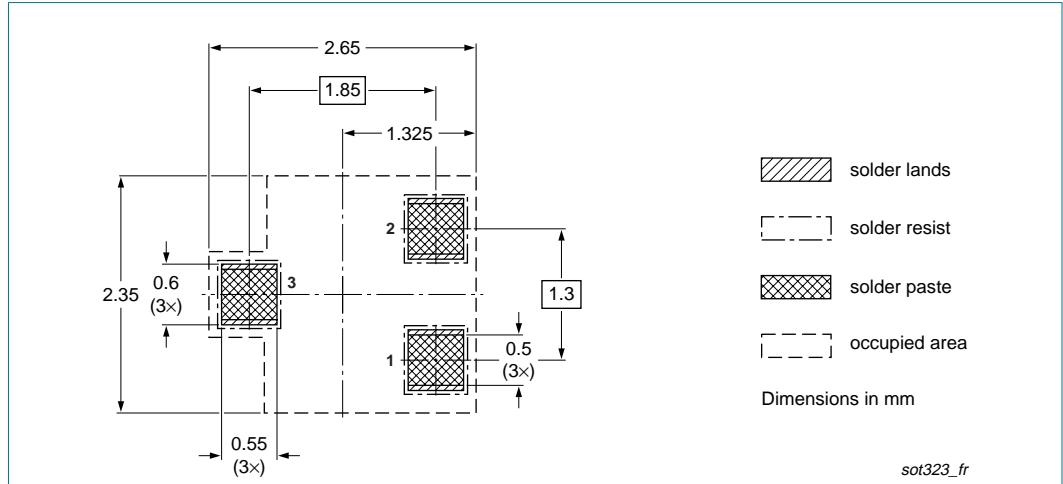


Fig 8. Reflow soldering footprint SOT323 (SC-70)

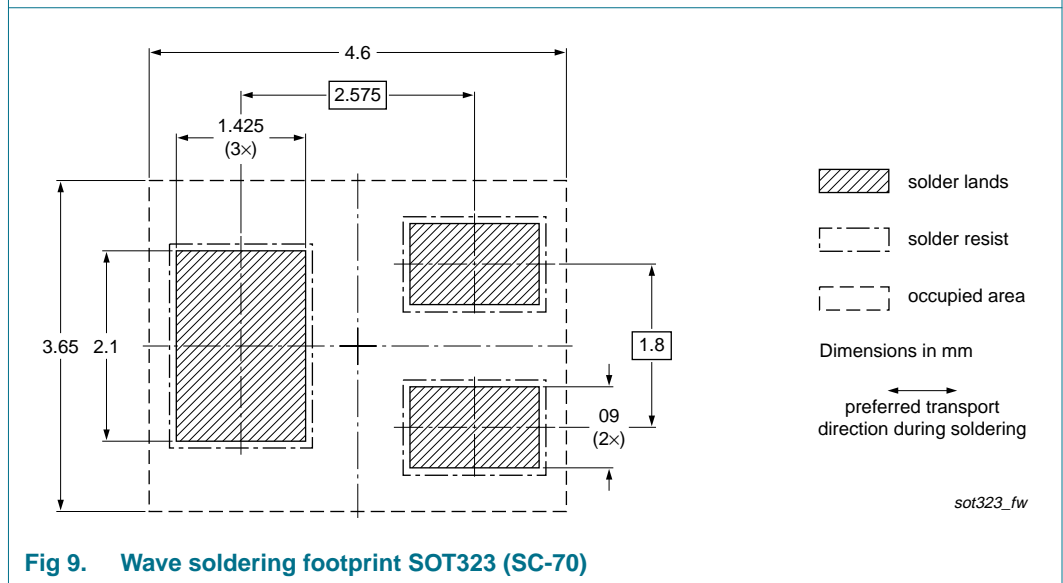


Fig 9. Wave soldering footprint SOT323 (SC-70)

12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAS21W_SER_1	20091009	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

13.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

13.3 Disclaimers

General — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental

damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

Terms and conditions of sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

13.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

14. Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

15. Contents

1 Product profile 1

1.1 General description 1

1.2 Features 1

1.3 Applications 1

1.4 Quick reference data 1

2 Pinning information 2

3 Ordering information 2

4 Marking 3

5 Limiting values 3

6 Thermal characteristics 4

7 Characteristics 4

8 Test information 6

8.1 Quality information 6

9 Package outline 7

10 Packing information 7

11 Soldering 8

12 Revision history 9

13 Legal information 10

13.1 Data sheet status 10

13.2 Definitions 10

13.3 Disclaimers 10

13.4 Trademarks 10

14 Contact information 10

15 Contents 11

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.



© NXP B.V. 2009.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 9 October 2009

Document identifier: BAS21W_SER_1